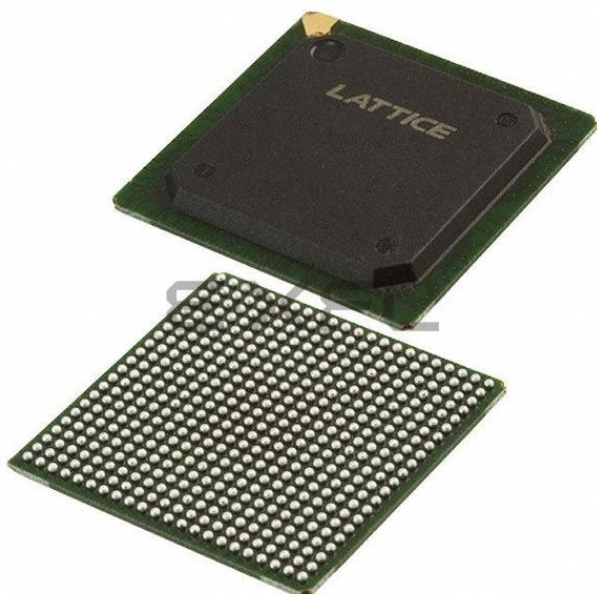




Welcome to [E·XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

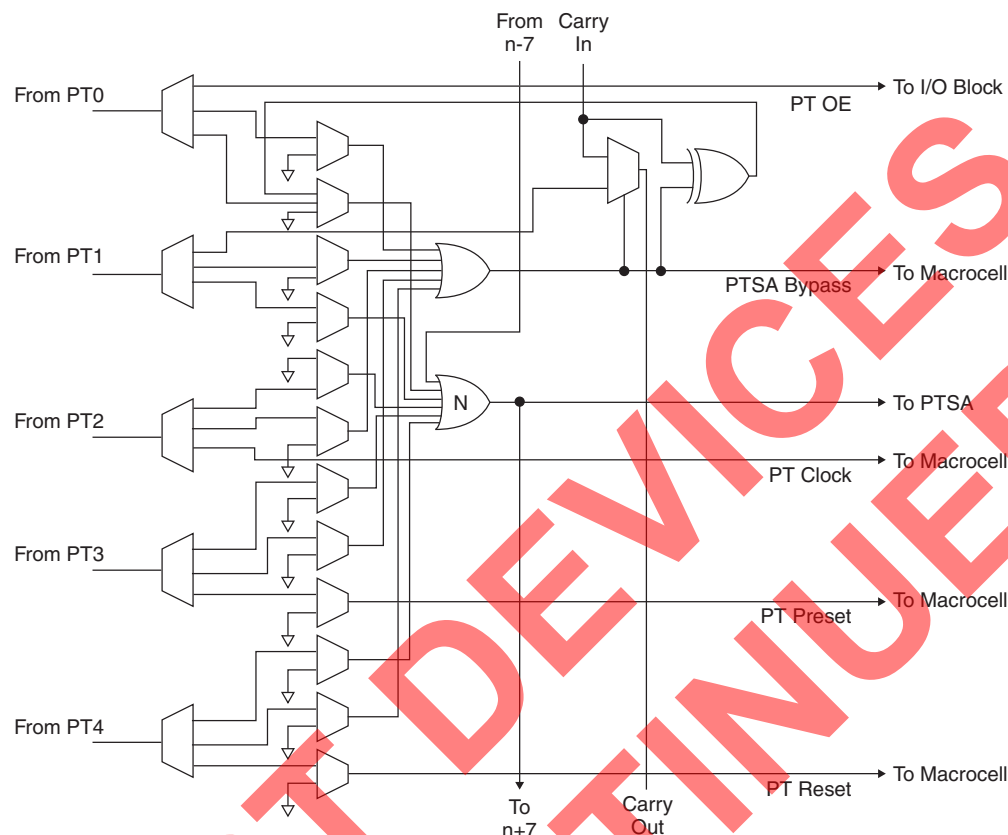
Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	4.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	512
Number of Gates	-
Number of I/O	253
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5512mv-45f484c



Product Line	Ordering Part Number	Product Status	Reference PCN
LC51024MV	LC51024MV-52F484C	Active / Orderable	
	LC51024MV-52FN484C		
	LC51024MV-75F484C		
	LC51024MV-75FN484C		
	LC51024MV-75F484I		
	LC51024MV-75FN484I		
	LC51024MV-52F672C		
	LC51024MV-52FN672C		
	LC51024MV-75F672C		
	LC51024MV-75FN672C		
	LC51024MV-75F672I		
	LC51024MV-75FN672I		
LC51024MB	LC51024MB-52F484C	Discontinued	PCN#09-10
	LC51024MB-52FN484C		
	LC51024MB-75F484C		
	LC51024MB-75FN484C		
	LC51024MB-75F484I		
	LC51024MB-75FN484I		
	LC51024MB-52F672C		
	LC51024MB-52FN672C		
	LC51024MB-75F672C		
	LC51024MB-75FN672C		
	LC51024MB-75F672I		
	LC51024MB-75FN672I		
LC51024MC	LC51024MC-52F484C	Discontinued	PCN#09-10
	LC51024MC-52FN484C		
	LC51024MC-75F484C		
	LC51024MC-75FN484C		
	LC51024MC-75F484I		
	LC51024MC-75FN484I		
	LC51024MC-52F672C		
	LC51024MC-52FN672C		
	LC51024MC-75F672C		
	LC51024MC-75FN672C		
	LC51024MC-75F672I		
	LC51024MC-75FN672I		

Figure 6. Dual-OR PT Sharing Array

Product Term Sharing Array

The Product Term Sharing Array (PTSA) consists of 32 inputs from the Dual-OR Array (Expandable PTSA OR) and 32 outputs directly to the macrocells. Each output is the OR term of any combination of the seven Expandable PTSA OR terms connected to that output. Every Nth macrocell is connected to N-3, N-2, N-1, N, N+1, N+2 and N+3 PTSA OR terms via a programmable connection. This wraps around the logic, for example, Macrocell 0 gets its logic from 29, 30, 31, 0, 1, 2, 3. The Expandable PTSA OR used in conjunction with the PTSA allows wide functions to be implemented easily and efficiently. Without using the Expandable PTSA OR capability, the greatest number of product terms that can be included in a single function with one pass of delay is 35. Up to 160 product terms can be included in a single function through the use of the expandable PTSA OR capability. Figure 7 shows the graphical representation of the PTSA.

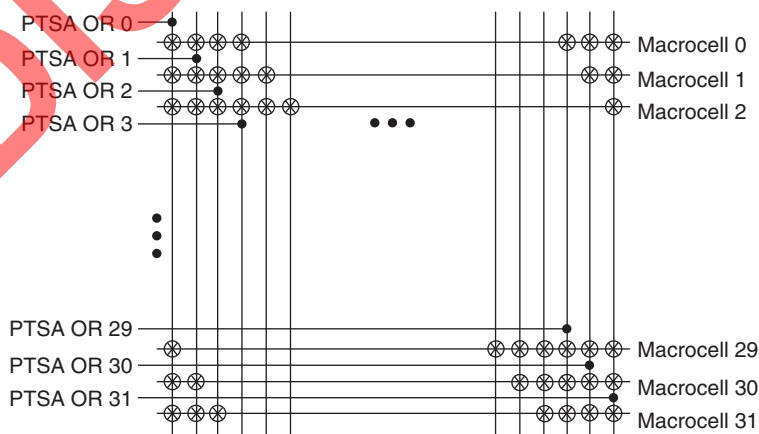
Figure 7. Product Term Sharing Array (PTSA)

Table 4. MFB Memory Configuration

Memory Mode	Max. Configuration Size ¹
Dual-port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 8 512 x 16
Single-port, Pseudo Dual Port, FIFO	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 8 1,024 x 16 512 x 32
CAM	128 x 48

1. Smaller configurations are possible.

Input and Output

The data input and control signals to a MFB in memory mode are generated from inputs from the routing. Data signals are only available in the true non-inverted format. True or complemented versions of the inputs are available for generating the control signals. Data and flag outputs are fed from the MFB to the GRP and OSA. Unused inputs and outputs are not accessible in memory mode.

ROM Operation

In each of the memory modes it is possible to specify the power-on state of each bit in the memory array. This allows the memory to be used as ROM if desired.

Increased Depth And Width

Designs that require a memory depth or width that is greater than that support by a single MFB can be supported by cascading multiple blocks. For dual port, single port, and pseudo dual port modes additional width is easily provided by sharing address lines. Additional depth is supported by multiplexing the RAM output. For FIFO and CAM modes additional width is supported through the cascading of MFBs.

The Lattice design tools automatically combine blocks to support the memory size specified in the user's design.

Bus Size Matching

All of the memory modes apart from CAM mode support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies this mapping scheme applies to each port.

Output Sharing Array (OSA)

A number of I/O pads are available in each sysIO bank to route the selected number of macrocells from the MFB outputs directly to the I/O pads in logic mode. In the ispXPLD 5000MX, the large number of inputs and PTs to the MFB as well as the presence of the PTSA can cover most routing flexibility of signals to I/O cells. The Output Sharing Array gives additional routing capability and I/O access to an MFB when a wide output function takes up the whole MFB and cannot be easily divided across multiple MFBs. By using the OSA, the wide output function, such as 32-bit FIFO, can have all of its output signals from the one MFB routed to I/O cells. In a given I/O block, the wide output functions must share the I/O pads with other logic functions.

The OSA bypass option routes the MFB signal directly to the I/O cell, allowing a direct connection to the I/O cell. The logic functions use the option to provide faster speed to the outputs. The Logic Signal Connection tables list the OSA bypass as the primary macrocell and OSA options as alternate macrocells. Similarly, the Alternate Input listing in the table shows the alternate macrocell input connection for a given I/O pin. Figure 17 shows the alternate macrocell connections in an I/O cell.

sysIO Banks

The ispXPLD 5000MX devices are divided into four sysIO banks, consisting of multiple I/O cells, where each bank is capable of supporting 16 different I/O standards. Each sysIO bank has its own I/O voltage (V_{CCO}) and reference voltage (V_{REF}) resources allowing complete independence from the others.

I/O Cell

The I/O cell of the ispXPLD 5000MX devices contains an output enable (OE) MUX, a programmable tri-state output buffer, a programmable input buffer, and programmable bus-maintenance circuitry.

The I/O cell receives inputs from its associated macrocells and the device pin. The I/O cell has a feedback line to its associated macrocells and a direct path to GRP. The output enable (OE) MUX selects the OE signal per I/O cell. The inputs to the OE MUX are the four global PTOE signals, PTOE and the two GOE signals. The OE MUX also has the ability to choose either the true or inverse of each of these signals. The output of the OE MUX goes through a logical AND with the TOE signal to allow easy tri-stating of the outputs for testing purposes. The MFBs are grouped into segments of four for the purpose of generating Shared PTOE signals. Each Shared PTOE signal is derived from PT 163 from one of the four MFBs. Table 10 shows the segments. The PTOE signal is derived from the first product term in each macrocell cluster, which is directly routed to the OE MUX. Therefore, every I/O cell can have a different OE signal. Figure 17 is a graphical representation of the I/O cell.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}^1	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCO} - 0.2V)$	—	—	10	μA
		$(V_{CCO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	40	μA
I_{IH}^4	Input High Leakage Current	$3.6V < V_{IN} \leq 5.5V$ and $3.0V \leq V_{CCO} \leq 3.6V$	—	—	3	mA
I_{PU}^3	I/O Active Pullup Current	$0 \leq V_{IN} \leq 0.7 V_{CCO}$	-30	—	-150	μA
I_{PD}	I/O Active Pulldown Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	150	μA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	μA
C1	I/O Capacitance ²	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	8	—	pf
C2	Clock Capacitance ²	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	8	—	pf
C3	Global Input Capacitance ²	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. $T_A = 25^\circ C$, $f = 1.0MHz$

3. I_{PU} on JTAG pins has a maximum of $-175\mu A$ for 5512MX devices.

4. 5V tolerant inputs and I/Os should be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$. The JTAG and sysCONFIG ports are not included for the 5V tolerant interface.

sysIO Recommended Operating Conditions

Standard	V _{CCO} (V) ²			V _{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVC MOS 3.3	3.0	3.3	3.6	—	—	—
LVC MOS 2.5	2.3	2.5	2.7	—	—	—
LVC MOS 1.8 ¹	1.65	1.8	1.95	—	—	—
LV TTL	3.0	3.3	3.6	—	—	—
PCI 3.3	3.0	3.3	3.6	—	—	—
AGP-1X	3.15	3.3	3.45	—	—	—
SSTL 2	2.3	2.5	2.7	1.15	1.25	1.35
SSTL 3	3.0	3.3	3.6	1.3	1.5	1.7
CTT 3.3	3.0	3.3	3.6	1.35	1.5	1.65
CTT 2.5	2.3	2.5	2.7	1.35	1.5	1.65
HSTL Class I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL Class III	1.4	1.5	1.6	—	0.9	—
HSTL Class IV	1.4	1.5	1.6	—	0.9	—
GTL+	1.4	—	3.6	0.882	1.0	1.122
LVDS	2.3	2.5/3.3	3.6	—	—	—

1. Design tools default setting.

2. Inputs are independent of V_{CCO} setting. However, V_{CCO} must be set within the valid operating range for one of the supported standards.

ispXPLD 5000MX Family External Switching Characteristics^{1, 2, 3}

Over Recommended Operating Conditions

Parameter	Description	-4		-45		-5		-52		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	Data Propagation Delay, 5-PT Bypass	—	4.0	—	4.5	—	5.0	—	5.2	—	7.5	ns
t_{PD_PTSA}	Data propagation delay	—	4.8	—	5.7	—	6.0	—	6.5	—	9.5	ns
t_S	MFB Register Setup Time Before Clock, 5-PT Bypass	2.2	—	2.8	—	2.8	—	3.0	—	4.5	—	ns
t_{S_PTSA}	MFB Register Setup Time Before Clock	2.5	—	3.1	—	3.1	—	3.6	—	5.5	—	ns
t_{SIR}	MFB Register Setup Time Before Clock, Input Register Path	1.0	—	1.0	—	1.0	—	0.5	—	1.7	—	ns
t_H	MFB Register Hold Time Before Clock, 5-PT Bypass	0.0	—	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	MFB Register Hold Time Before Clock	0.0	—	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	MFB Register Hold Time Before Clock, Input Register Path	0.5	—	0.5	—	0.5	—	1.0	—	1.3	—	ns
t_{CO}	MFB Register Clock-to-Out-put Delay	—	2.8	—	3.0	—	3.2	—	3.7	—	5.0	ns
t_R	External Reset Pin to Output Delay	—	4.0	—	4.5	—	5.0	—	5.0	—	7.5	ns
t_{RW}	Reset Pulse Duration	1.8	—	1.8	—	1.8	—	2.0	—	3.0	—	ns
$t_{LPTOE/DIS}$	Input to Output Local Product Term Output Enable/Disable	—	6.0	—	7.0	—	7.5	—	8.5	—	10.5	ns
$t_{SPTOE/DIS}$	Input to Output Shared Product Term Output Enable/Disable	—	6.0	—	7.0	—	7.5	—	8.5	—	10.5	ns
$t_{GOE/DIS}$	Global OE Input to Output Enable/Disable	—	4.5	—	5.5	—	5.5	—	6.5	—	7.5	ns
t_{CW}	Clock Width, High or Low	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{GW}	Gate Width Low (for Low Transparent) or High (for High Transparent)	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{WIR}	Input Register Clock Width, High or Low	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{SKEW}	Clock-to-Out Skew, Block Level	—	0.6	—	0.6	—	0.6	—	0.6	—	1.0	ns
f_{MAX}^4	Clock Frequency with Internal Feedback	—	300	—	275	—	250	—	250	—	150	MHz
$f_{MAX} (Ext.)$	Clock Frequency with External Feedback, $1/(t_S + t_{CO})$	—	200	—	171	—	166	—	149	—	105	MHz
$f_{MAX} (Tog.)$	Clock Frequency Max. Toggle	—	333	—	333	—	333	—	277	—	200	MHz
$f_{MAX} (CAMC)^5$	Clock Frequency to CAM (Configure Mode)	—	280	—	280	—	230	—	230	—	168	MHz
$f_{MAX} (CAM)^5$	Clock Frequency to CAM (Compare Mode)	—	150	—	150	—	150	—	135	—	90	MHz

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{CASC}	Additional Delay for PT Cascading between MFBs	—	—	0.71	—	0.80	—	0.89	—	0.92	—	1.33	ns
t _{CICOMFB}	Carry Chain Delay, MFB to MFB	—	—	0.35	—	0.39	—	0.44	—	0.46	—	0.66	ns
t _{CICOMC}	Carry Chain Delay, Macro-Cell to Macro-Cell	—	—	0.10	—	0.11	—	0.13	—	0.13	—	0.19	ns
t _{FLAG}	Routing Delay for Extended Function Flags	—	—	2.62	—	2.94	—	3.27	—	3.40	—	4.91	ns
t _{FLAGEXP}	Additional Flag Delay when Expanding Data Widths	t _{FLAGFULL} , t _{FLAGAFULL} , t _{FLAGEMPTY} , t _{FLAGAEMPTY}	—	2.57	—	2.89	—	3.21	—	3.34	—	4.82	ns
t _{SUM}	Counter Sum Delay	t _{PTSA}	—	0.80	—	0.90	—	1.00	—	1.04	—	1.50	ns
Optional Adjusters													
t _{BLA}	Block Loading Adder	t _{ROUTE}	—	0.04	—	0.04	—	0.05	—	0.05	—	0.07	ns
t _{EXP}	PT Expander Adder	t _{ROUTE}	—	0.53	—	0.60	—	0.66	—	0.69	—	0.99	ns
t _{INDIO}	Additional Delay for the Input Register	t _{INREG}	—	0.50	—	0.56	—	0.63	—	0.65	—	0.94	ns
t _{PLL_SEC_DELAY}	Secondary PLL Output Delay	t _{PLL_DELAY}	—	0.91	—	0.91	—	0.91	—	0.91	—	0.91	ns
t _{INEXP}	MFB Input Extender	t _{ROUTE}	—	0.62	—	0.70	—	0.78	—	0.81	—	1.16	ns
Input and Output Buffer Delays													
t _{IOI}	Input Buffer Selection Adder	t _{GCLK_IN} , t _{IN} , t _{GOE} , t _{RST}	Refer to sysIO Adjuster Tables										ns
t _{IOO}	Output Buffer Selection Adder	t _{BUF}											ns
FIFO													
t _{FIFOWCLKS}	Write Data Setup before Write Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{FIFOWCLKH}	Write Data Hold after Write Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{FIFOCLKSKEW}	Opposite Clock Cycle Delay	—	—	1.40	—	1.40	—	1.76	—	1.76	—	1.83	ns
t _{FIFOFULL}	Write Clock to Full Flag Delay	—	—	3.08	—	3.08	—	3.85	—	3.85	—	4.00	ns
t _{FIFOAFULL}	Write Clock to Almost Full Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns
t _{FIFOEMPTY}	Read Clock to Empty Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns
t _{FIFOAEMPTY}	Read Clock to Almost Empty Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{CAMWMSKS}	Write Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{CAMWMSKH}	Write Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMRSTO}	Reset to CAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
t _{CAMRSTR}	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
t _{CAMRSTPW}	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
CAM – Compare Mode													
t _{CAMDATAS}	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
t _{CAMDATAH}	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMENMSKS}	Enable Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t _{CAMENMSKH}	Enable Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{CAMCASC}	CAM Width Expansion Delay	—	—	0.40	—	0.40	—	0.50	—	0.50	—	0.51	ns
t _{CAMCO}	Clock to Output (Address Out) Delay	—	—	6.19	—	6.13	—	6.81	—	6.61	—	9.63	ns
t _{CAMMATCH}	Clock to Match Flag Delay	—	—	6.19	—	6.13	—	6.07	—	6.61	—	10.22	ns
t _{CAMMMATCH}	Clock to Multi-Match Flag Delay	—	—	5.50	—	5.50	—	6.38	—	6.38	—	7.72	ns
t _{CAMRSTFLAG}	CAM Reset to Flags Delay	—	—	3.16	—	3.16	—	3.95	—	3.95	—	4.11	ns
Single Port RAM													
t _{SPADDDATA}	Address to Data Delay	—	—	5.97	—	5.97	—	5.97	—	5.97	—	7.76	ns
t _{SPMSS}	Memory Select Setup Before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t _{SPMSH}	Memory Select Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t _{SPCES}	Clock Enable Setup before Clock Time	—	2.30	—	2.30	—	2.30	—	2.30	—	9.80	—	ns
t _{SPCEH}	Clock Enable Hold time after Clock Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
t _{SPADDS}	Address Setup before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns

ispXPLD 5000MX Family Timing Adders

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{IOI} Input Adjusters													
LVTTTL_in	Using 3.3V TTL	t _{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS_18_in	Using 1.8V CMOS	t _{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS_25_in	Using 2.5V CMOS	t _{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS_33_in	Using 3.3V CMOS	t _{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	Using AGP 1x	t _{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
CTT25_in	Using CTT 2.5V	t _{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
CTT33_in	Using CTT 3.3V	t _{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
GTL+_in	Using GTL+	t _{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_I_in	Using HSTL 2.5V, Class I	t _{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_in	Using HSTL 2.5V, Class III	t _{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_in	Using HSTL 2.5V, Class IV	t _{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_in	Using Low Voltage Differential Signaling (LVDS)	t _{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
LVPECL_in	Using Low Voltage PECL	t _{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
PCI_in	Using PCI	t _{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
SSTL2_I_in	Using SSTL 2.5V, Class I	t _{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL2_II_in	Using SSTL 2.5V, Class II	t _{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_in	Using SSTL 3.3V, Class I	t _{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL3_II_in	Using SSTL 3.3V, Class II	t _{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
t _{IOO} Output Adjusters – Output Signal Modifiers													
Slow Slew	Using Slow Slew (LVTTTL and LVC MOS Outputs Only)	t _{IOBUF} , t _{IOEN}	—	0.9	—	0.9	—	0.9	—	0.9	—	0.9	ns
t _{IOO} Output Adjusters – Output Configurations													
LVTTTL_out	Using 3.3V TTL Drive	t _{IOBUF} , t _{IOEN} , t _{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVC MOS_18_4mA_out	Using 1.8V CMOS Standard, 4mA Drive	t _{IOBUF} , t _{IOEN} , t _{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
LVC MOS_18_5.33mA_out	Using 1.8V CMOS Standard, 5.33mA Drive	t _{IOBUF} , t _{IOEN} , t _{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns

ispXPLD 5000MX Family Timing Adders (Continued)

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
LVC MOS_18_8mA_out	Using 1.8V CMOS Standard, 8mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS_18_12mA_out	Using 1.8V CMOS Standard, 12mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVC MOS_25_4mA_out	Using 2.5V CMOS Standard, 4mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVC MOS_25_5.33mA_out	Using 2.5V CMOS Standard, 5.33 mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
LVC MOS_25_8mA_out	Using 2.5V CMOS Standard, 8mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns
LVC MOS_25_12mA_out	Using 2.5V CMOS Standard, 12mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns
LVC MOS_25_16mA_out	Using 2.5V CMOS Standard, 16mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns
LVC MOS_33_4mA_out	Using 3.3V CMOS Standard, 4mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVC MOS_33_5.33mA_out	Using 3.3V CMOS Standard, 5.33mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVC MOS_33_8mA_out	Using 3.3V CMOS Standard, 8mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.8	—	0.8	—	0.8	—	0.8	—	0.8	ns
LVC MOS_33_12mA_out	Using 3.3V CMOS Standard, 12mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVC MOS_33_16mA_out	Using 3.3V CMOS Standard, 16mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVC MOS_33_20mA_out	Using 3.3V CMOS Standard, 20mA Drive	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
AGP_1X_out	Using AGP 1x Standard	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
CTT25_out	Using CTT 2.5V	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
CTT33_out	Using CTT 3.3V	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.2	—	0.2	—	0.2	—	0.2	—	0.2	ns
GTL+_out	Using GTL+	t_{IOBUF} , t_{IOEN} , t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns

Boundary Scan Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min	Max	Units
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	8	—	ns
t_{BTH}	TCK [BSCAN] hold time	10	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	10	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Power Estimation Equations

$$ICC = ICC_DC + IMFB_CPLD + IMFB_SRAM/PDPRAM/FIFO + IMFB_DPRAM + IMFB_CAM + IPLL_D$$

ICC_DC

Use the appropriate value for 5000MC (1.8V power supply) or 5000MV/B (2.5V/3.3V power supply) from the data sheet.

IMFB_CPLD

$$= ((K0 * CPLD \text{ MFB inputs} + K1 * CPLD \text{ Logical Product Terms} + K2 * CPLD \text{ GRP from MFB} + K3 * CPLD \text{ GRP from IFB}) * AF + K4) * \text{FREQ} / 1000\mu\text{A}/\text{mA}$$

IMFB_CAM

$$= \text{CAM Memory MFBs} * ((\text{FREQ} * K8) + K9) \text{ (CAM operating in typical mode)}$$

IMFB_SRAM/PDPRAM/FIFO

$$= (\text{WR_PERCENT} * (K1 + \text{WR_PERCENT} * 8 * K0 + K10 + K11) + \text{RD_PERCENT} * (K1 + 128 * \text{RD_PERCENT} * K0 + 8 * \text{OSW_PERCENT} * K2)) * \text{SRAM/PDPRAM/FIFO Memory MFBs} * \text{FREQ} / 1000\mu\text{A}/\text{mA}$$

IMFB_DPRAM

$$= (\text{WR_PERCENT} * (2 * K1 + 2 * \text{WR_PERCENT} * 8 * K0 + K10 + K11) + \text{RD_PERCENT} * (2 * K1 + 2 * 128 * \text{RD_PERCENT} * K0 + 8 * \text{OSW_PERCENT} * K2)) * \text{DPRAM Memory MFBs} * \text{FREQ} / 1000\mu\text{A}/\text{mA}$$

IPLL_D

$$= K5 * \text{PLL_FREQ} * \text{number of PLLs used. IPLD_D is the PLL digital component of the VCC supply current.}$$

Analog portion of PLL supply current consumption, from PLL power pin:

$$IPLL_A = (K6 * \text{PLL_FREQ} + K7) * \text{number of PLLs used}$$

Notes:

- ICC = Current consumption of VCC power supply (mA)
- ICC-DC = ICC DC component – Current consumption at 0Mhz (mA)
- IMFB_CPLD = CPLD (non-memory logic) current consumption (mA)
- IMFB_SRAM/PDPRAM/FIFO = Current consumption for SRAM, PDPRAM, and FIFO (mA)
- IMFB_DPRAM = Current consumption for DPRAM (mA)
- IMFB_CAM = Current consumption for CAM (mA)
- IPLD_D = PLL Current consumption of digital VCC power supply (mA)
- IPLD_A = PLL analog power pin current consumption (VCCP pin)

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
3	34N	E30	-	-	E31	H14
3	34P	E28	-	-	E29	G16
3	35N	E26	-	-	E27	G15
3	35P	E24/PLL_FBK1	-	-	E25	F15
3	36N	E22/PLL_RST1	E27	F27	E23	H12
3	36P	E21	E26	F26	-	G14
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)
3	37N	E20	E25	F25	-	F16
-	-	VCCO3	-	-	-	VCCO3
3	37P	E18	E24	F24	E19	E16
-	-	GND	-	-	-	GND
3	38N	E16	E23	F23	E17	G13
3	38P	E14	E22	F22	E15	G12
3	39N	E12	E21	F21	E13	F14
3	39P	E10/CLK_OUT1	E20	F20	E11	E15
-	-	VCC	-	-	-	VCC
3	40N	E8	E19	F19	E9	D12
3	40P	E6	E18	F18	E7	B14
3	41N	E5	E17	F17	-	C13
3	41P	E4	E16	F16	-	A14
3	42N	E2	E31	F31	E3	A13
3	42P	E0	E30	F30	E1	B13
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)
-	-	VCCO3	-	-	-	VCCO3
3	43N	F30	E15	F15	F31	B11
3	43P	F28	E14	F14	F29	C11
3	44N	F26	E13	F13	F27	B10
3	44P	F24	E12	F12	F25	A10
3	45N	F22	E11	F11	F23	C10
3	45P	F21	E10	F10	-	D10
3	46N	F20	E9	F9	-	C9
3	46P	F18	E8	F8	F19	E9
3	47N	F16/VREF3	E29	F29	F17	D9
3	47P	F14	E28	F28	F15	F9
3	48N	F12	E7	F7	F13	A9
3	48P	F10	E6	F6	F11	F8
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)
3	49N	F8	E5	F5	F9	E8
-	-	VCCO3	-	-	-	VCCO3
3	49P	F6	E4	F4	F7	A8
3	50N	F5	E3	F3	-	B9
3	50P	F4	E2	F2	-	D8
-	-	VCC	-	-	-	VCC

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	TCK	-	-	-	J6	T1
-	-	TDO	-	-	-	K2	V1
1	0P	A30/DATA0	C0	A0	A31	K3	W1
1	0N	A28/DATA1	C1	A1	A29	J3	Y1
1	1P	A26/DATA2	C2	A2	A27	J5	P3
1	1N	A24/DATA3	C3	A3	A25	J4	R3
1	2P	A22/DATA4	C4	A4	A23	L2	T2
1	2N	A20/DATA5	C5	A5	A21	M1	U2
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	3P	A18/DATA6	C6	A6	A19	K4	V2
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	3N	A16/DATA7	C7	A7	A17	L3	W2
-	-	GND	-	-	-	GND	GND
1	4P	A14/INITB	C8	A8	A15	K5	R4
1	4N	A12/CSB	C9	A9	A13	L5	T4
1	5P	A10/READ	C10	A10	A11	N1	R6
1	5N	A8/CCLK	C11	A11	A9	M2	R5
1	6P	A6	-	-	A7	—	U3
-	-	VCC	-	-	-	VCC	VCC
1	6N	A4	-	-	A5	P1	V3
1	7P	A2	-	-	A3	M3	Y2
1	7N	A0	-	-	A1	L4	W3
1	8P	B30	D0	-	B31	N2	U5
1	8N	B28	D2	-	B29	P2	T5
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	9P	B26	D4	-	B27	R1	U4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	9N	B24	D6	-	B25	R2	V4
1	10P	B22	D8	-	B23	T2	AA3
1	10N	B20	D10	-	B21	T3	AB3
1	-	B18	D12	-	B19	—	Y4
-	-	DONE	-	-	-	M4	AA4
1	11P	B14	-	-	B15	—	AB2
1	11N	B12	-	-	B13	—	U6
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	12P	B10	-	-	B11	—	V5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	12N	B8	-	-	B9	—	W6
1	13P	B6	C12	A12	B7	N3	AB4
1	13N	B4	C13	A13	B5	P4	AB5
1	14P	B2	C14	A14	B3	N5	T6
1	14N	B0	C15	A15	B1	M6	U7
-	-	PROGRAMB	-	-	-	R3	W5

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
1	-	C28	D14	-	C29	P5	U8
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	15P	C26	D16	-	C27	T4	V6
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	15N	C24	D18	-	C25	T5	V7
-	-	GND	-	-	-	GND	GND
1	16P	C22	D20	-	C23	R4	Y5
-	-	VCC	-	-	-	VCC	VCC
1	16N	C20	D22	-	C21	N6	AA5
1	17P	C18	-	-	C19	R5	Y6
1	17N	C16	-	-	C17	P6	Y7
1	18P	C14	-	-	C15	-	AA6
1	18N	C12	-	-	C13	-	AA7
1	19P	C10	-	-	C11	-	W7
1	19N	C8	-	-	C9	M7	V8
1	20P	C6	-	-	C7	T6	W8
1	20N	C4	-	-	C5	R6	U9
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
-	-	CFG0	-	-	-	L8	U10
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	21P	C0	C16	A16	C1	T7	AB7
1	21N	D30	C17	A17	D31	R7	AA8
1	22P	D28	C18	A18	D29	N7	AB8
1	22N	D26	C19	A19	D27	P7	AB9
1	23P	D24	C20	A20	D25	T8	W9
1	23N	D22	C21	A21	D23	R8	Y9
1	24P	D20	C22	A22	D21	M8	AB10
1	24N	D18	C23	A23	D19	P8	AA10
1	-	D16/VREF1	-	-	D17	L9	W10
1	25P	D14	C24	A24	D15	N8	Y10
1	25N	D12	C25	A25	D13	M9	Y11
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	26P	D10	C26	A26	D11	N10	V9
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	26N	D8	C27	A27	D9	T9	V10
1	27P	D6	C28	A28	D7	T10	AA11
-	-	GND	-	-	-	GND	GND
1	27N	D4	C29	A29	D5	R9	AB11
-	-	VCC	-	-	-	VCC	VCC
1	28P	D2	C30	A30	D3	P9	U11
1	28N	D0	C31	A31	D1	N9	V11
2	29P	E0	F0	H0	E1	T11	AB12
-	-	VCC	-	-	-	VCC	VCC

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	126N	S26	S13	-	S27	—	C4
0	126P	S24	S12	-	S25	—	D5

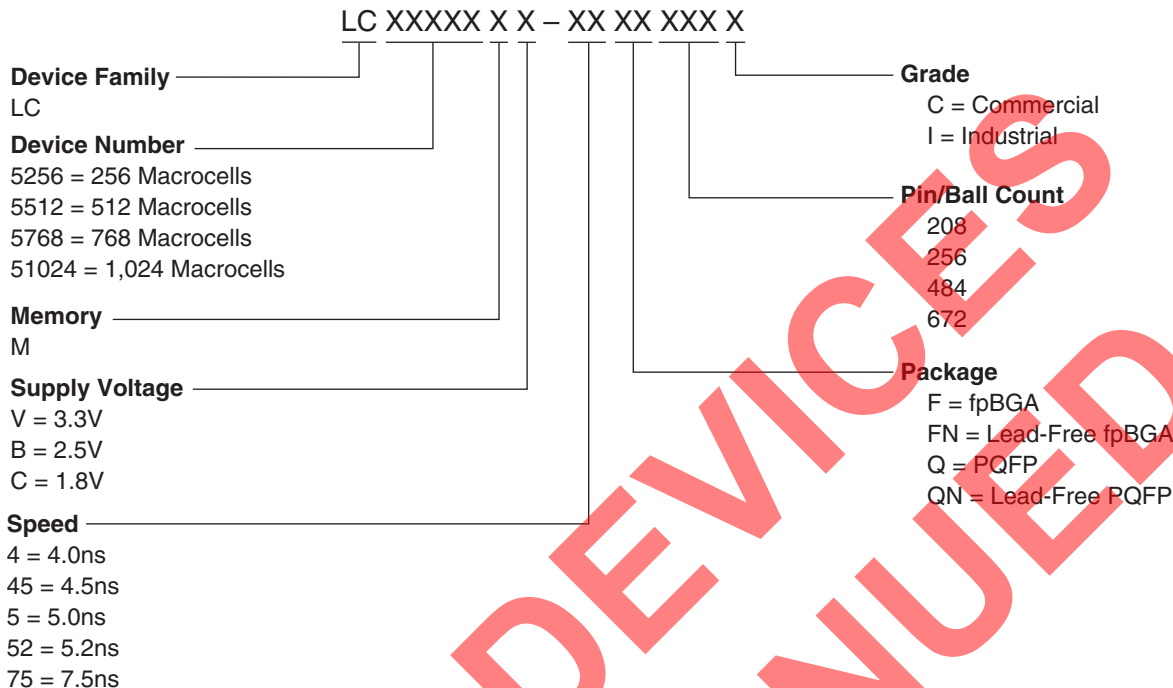
Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

SELECT DEVICES
DISCONTINUED

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	31P	G26	H16	-	G27	V6	AB7
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	31N	G24	H18	-	G25	V7	AC7
-	-	GND	-	-	-	GND	GND
1	32P	G22	H20	-	G23	Y5	AB6
-	-	VCC	-	-	-	VCC	VCC
1	32N	G20	H22	-	G21	AA5	AC6
1	33P	G18	-	-	G19	Y6	AC8
1	33N	G16	-	-	G17	Y7	AC9
1	34P	G14	-	-	G15	AA6	AC5
1	34N	G12	-	-	G13	AA7	AD4
1	35P	G10	-	-	G11	W7	AD5
1	35N	G8	-	-	G9	V8	AD6
1	36P	G6	-	-	G7	W8	AD7
1	36N	G4	-	-	G5	U9	AD8
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
-	-	CFG0	-	-	-	U10	AE3
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	37P	G0	G16	E16	G1	AB7	AD9
1	37N	H30	G17	E17	H31	AA8	AD10
1	38P	H28	G18	E18	H29	AB8	AE4
1	38N	H26	G19	E19	H27	AB9	AE5
1	39P	H24	G20	E20	H25	W9	AE6
1	39N	H22	G21	E21	H23	Y9	AE7
1	40P	H20	G22	E22	H21	AB10	AE8
1	40N	H18	G23	E23	H19	AA10	AE9
1	-	H16/VREF1	-	-	H17	W10	AE10
1	41P	H14	G24	E24	H15	Y10	AF3
1	41N	H12	G25	E25	H13	Y11	AF4
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	42P	H10	G26	E26	H11	V9	AF5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	42N	H8	G27	E27	H9	V10	AF6
1	43P	H6	G28	E28	H7	AA11	AF7
-	-	GND	-	-	-	GND	GND
1	43N	H4	G29	E29	H5	AB11	AF8
-	-	VCC	-	-	-	VCC	VCC
1	44P	H2	G30	E30	H3	U11	AF9
1	44N	H0	G31	E31	H1	V11	AF10
2	45P	I0	J0	L0	I1	AB12	AF17
-	-	VCC	-	-	-	VCC	VCC
2	45N	I2	J1	L1	I3	AA12	AF18

Part Number Description



Ordering Information

Note: For voltage families offered in industrial temperature grades and for all but the slowest commercial speed grade, the speed grades on these devices are dual marked. For example, the commercial speed grade -45XXXXC is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade is marked as commercial grade only. In addition, the fastest commercial speed grade (-5) for the LC5768MB/MV devices, at Lattice's discretion, will utilize either a commercial grade only single-mark or a dual-mark format in conjunction with the slower industrial speed grade (-75).

Conventional Packaging

ispXPLD 5000MC (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t _{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MC	LC5256MC-4F256C	256	1.8	4.0	fpBGA	256	141	C
	LC5256MC-5F256C	256	1.8	5.0	fpBGA	256	141	C
	LC5256MC-75F256C	256	1.8	7.5	fpBGA	256	141	C
LC5512MC	LC5512MC-45Q208C	512	1.8	4.5	PQFP	208	149	C
	LC5512MC-75Q208C	512	1.8	7.5	PQFP	208	149	C
	LC5512MC-45F256C	512	1.8	4.5	fpBGA	256	193	C
	LC5512MC-75F256C	512	1.8	7.5	fpBGA	256	193	C
	LC5512MC-45F484C	512	1.8	4.5	fpBGA	484	253	C
	LC5512MC-75F484C	512	1.8	7.5	fpBGA	484	253	C

ispXPLD 5000MB (2.5V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t _{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-5F256I	256	2.5	5.0	fpBGA	256	141	I
	LC5256MB-75F256I	256	2.5	7.5	fpBGA	256	141	I
LC5512MB	LC5512MB-75Q208I	512	2.5	7.5	PQFP	208	149	I
	LC5512MB-75F256I	512	2.5	7.5	fpBGA	256	193	I
	LC5512MB-75F484I	512	2.5	7.5	fpBGA	484	253	I
LC5768MB	LC5768MB-75F256I	768	2.5	7.5	fpBGA	256	193	I
	LC5768MB-75F484I	768	2.5	7.5	fpBGA	484	317	I
LC51024MB	LC51024MB-75F484I	1024	2.5	7.5	fpBGA	484	317	I
	LC51024MB-75F672I	1024	2.5	7.5	fpBGA	672	381	I

ispXPLD 5000MV (3.3V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t _{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-4F256C	256	3.3	4.0	fpBGA	256	141	C
	LC5256MV-5F256C	256	3.3	5.0	fpBGA	256	141	C
	LC5256MV-75F256C	256	3.3	7.5	fpBGA	256	141	C
LC5512MV	LC5512MV-45Q208C	512	3.3	4.5	PQFP	208	149	C
	LC5512MV-75Q208C	512	3.3	7.5	PQFP	208	149	C
	LC5512MV-45F256C	512	3.3	4.5	fpBGA	256	193	C
	LC5512MV-75F256C	512	3.3	7.5	fpBGA	256	193	C
	LC5512MV-45F484C	512	3.3	4.5	fpBGA	484	253	C
	LC5512MV-75F484C	512	3.3	7.5	fpBGA	484	253	C
	LC5512MV-75F484C	512	3.3	7.5	fpBGA	484	253	C
LC5768MV	LC5768MV-5F256C	768	3.3	5.0	fpBGA	256	193	C
	LC5768MV-75F256C	768	3.3	7.5	fpBGA	256	193	C
	LC5768MV-5F484C	768	3.3	5.0	fpBGA	484	317	C
	LC5768MV-75F484C	768	3.3	7.5	fpBGA	484	317	C
LC51024MV	LC51024MV-52F484C	1024	3.3	5.2	fpBGA	484	317	C
	LC51024MV-75F484C	1024	3.3	7.5	fpBGA	484	317	C
	LC51024MV-52F672C	1024	3.3	5.2	fpBGA	672	381	C
	LC51024MV-75F672C	1024	3.3	7.5	fpBGA	672	381	C

ispXPLD 5000MV (3.3V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t _{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-5F256I	256	3.3	5.0	fpBGA	256	141	I
	LC5256MV-75F256I	256	3.3	7.5	fpBGA	256	141	I
LC5512MV	LC5512MV-75Q208I	512	3.3	7.5	PQFP	208	149	I
	LC5512MV-75F256I	512	3.3	7.5	fpBGA	256	193	I
	LC5512MV-75F484I	512	3.3	7.5	fpBGA	484	253	I
LC5768MV	LC5768MV-75F256I	768	3.3	7.5	fpBGA	256	193	I
	LC5768MV-75F484I	768	3.3	7.5	fpBGA	484	317	I
LC51024MV	LC51024MV-75F484I	1024	3.3	7.5	fpBGA	484	317	I
	LC51024MV-75F672I	1024	3.3	7.5	fpBGA	672	381	I